

SonoGage Resistivity and Wafer Thickness Measurement System (rt2)

Note: Since this equipment does not probe wafers while doing measurements, it can be used on new wafers to test them before mainstream processing.

Operating Procedures

Wafer Thickness measurement:

- Set controls to **THK, MAN** and **μ**.
- Put wafer on machine arm with flat towards you.
- Push start and the machine will measure the wafer thickness.
- This can be done more than once to get a statistical mean but it should not be necessary.
- When finished push start until the head is looking at the white square (the arm should be on the right)

Bulk Resistivity measurement:

- Set controls to **RES, AUTO** and **ohm-cm**.
- Put wafer on machine arm with the flat towards you.
- Push start and the machine will measure 3 places (left center and right) and then rotate the wafer and measure 3 places in that direction (top center and bottom).
- When finished push start until the head is looking at the white square (the arm should be on the right).

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